### Cascade Microtech, Inc.

#### **SPECIFICATION SHEET**



## Most accurate wafer-level multiport measurements

# Dual Z Probe

**High-Frequency Wafer Probe** 

For wafer-level testing of RF and microwave devices, there is no better solution than the  $|\mathbf{Z}|$  Probe. The patented technology used in the  $|\mathbf{Z}|$  Probe assures high-accuracy measurements with low contact resistance and superior impedance control. The RF / microwave signal makes only one transition to the coplanar contact structure within the shielded, air-isolated probe body. This maintains the signal integrity with stable performance over a wide temperature from 10 K to 300°C.

The Dual |Z| Probe has been enhanced with the cutting-edge 1MX<sup>TM</sup> technology. Electrical performance, especially insertion and return loss, has been advanced to levels superior to older technologies like thin-film and micro-coax probes. In addition, isolation (crosstalk) has been significantly improved resulting in a probe that delivers the highest accuracy for your wafer-level RF and microwave measurements.

Contacting the device under test (DUT) with the Dual  $|\mathbf{Z}|$  Probe is simple, highly repeatable and requires significantly less overtravel than conventional RF wafer probes. This is due to the robust design of the coplanar contact structure and the elimination of the microcoax cable. As the contacts can move independently of each other, an excellent contact quality is guaranteed regardless of the number of contacts. Additionally, this allows you to probe on three-dimensional structures and on wafers with pad-height deviation of up to 50  $\mu$ m.

The complete Cascade Microtech HF probe system includes the highly-accurate CSR family of calibration substrates for each pitch, which significantly reduces parasitic effects of calibration standards and drastically increases calibration accuracy. When used together with ProbeHeads<sup>TM</sup> and the powerful SussCal® Calibration Software, the Dual  $|\mathbf{Z}|$  Probe becomes the ultimate tool for all your HF wafer-level probing needs.

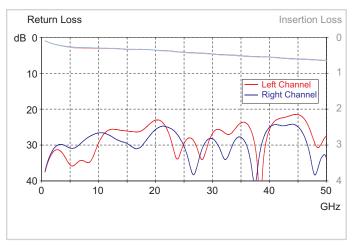
Thanks to the proven  $|\mathbf{Z}|$  Probe technology, the probe also has an extremely long lifetime. Cascade Microtech guarantees that the probe has a useful life of at least 1,000,000 contact cycles under standard use and overtravel.

FEATURES AND B	
Durability	Incredibly long lifetime
	Unparalleled repeatable and reliable contact quality
Flexibility	Suitable for automated testing
	Probe on most pad material with minimal damage
	Independent, long contact springs easily overcome pad height differences up to 50 µm
	Small structures such as 40 µm x 40 µm pads can be tested
	Excellent performance in vacuum environments and temperatures from 10 K to 300°C
	Available in GSGSG (up to 50 GHz), GSSG and SGS (both up to 18 GHz)
RF performance	Lowest insertion loss
	Lowest crosstalk
	Lowest contact resistance
	High power capability

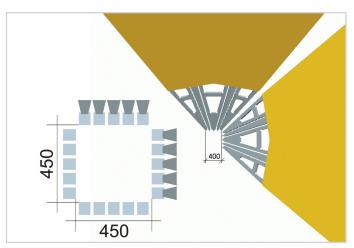
SPECIFICATIONS*			
Electrical Characteristics (50 GHz GSGSG)			
Characteristic impedance	50 Ω		
Return loss	≥ 17 dB DC to 50 GHz (50 µm to 250 µm)		
	≥ 15 dB DC to 50 GHz (500 µm)		
Insertion loss	< 0.8 dB DC to 50 GHz (50 μm to 250 μm)		
Crosstalk	≤ -43 dB DC to 50 GHz at 150 µm distance on ceramic		
RF maximum power	2 x 5 W (50 GHz)		
	2 x 9 W (20 GHz)		
	2 x 16 W (5 GHz)		
DC current	2 x maximum 1.5 A		
Internal crosstalk	< -30 dB DC to 50 GHz (air / SOL standards)		
Contact resistance on Au	< 6 mΩ		
Contact resistance on Al	< 30 mΩ		
Mechanical Characteristics			
Contact material	Nickel		
Insulator	RF dielectric		
Contact cycles on Al	> 1,000,000		
Contact spring pressure	10 N / mm		
Available standard pitches (µm)	100, 125, 150, 175, 200, 250, 500 μm		
Connector			
Туре	PC 2.4 mm (50 GHz)		
	PC 2.92 mm (other)		
Coupling torque	0.8 to 1.1 Nm (recommended)		

<sup>\*</sup> Data, design and specification depend on individual process conditions and can vary according to equipment configurations.

Not all specifications may be valid simultaneously.

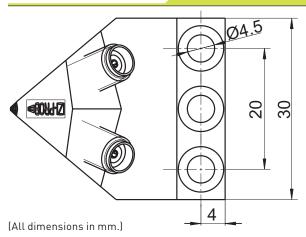


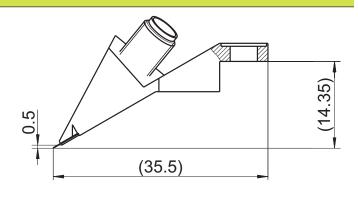
Uncalibrated performance of a Dual  $|\mathbf{Z}|$  Probe (50 GHz, GSGSG, pitch: 100  $\mu$ m).



NSEW configuration down to a minimum chip size of 450  $\mu m$  x 450  $\mu m$  (all dimensions in  $\mu m).$ 

### PHYSICAL DIMENSIONS







Dual |Z| Probe with 1MX technology.

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Data subject to change without notice

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Cascade Microtech, Inc. toll free: +1-800-550-3279 phone: +1-503-601-1000 email: cmi\_sales@cmicro.com

Cascade Microtech GmbH phone: +49-811-60005-0 email: cmg\_sales@cmicro.com Cascade Microtech Japan phone: +81-3-5615-5150 email: cmj\_sales@cmicro.com

Cascade Microtech Shanghai phone: +86-21-3330-3188 email: cmc\_sales@cmicro.com Cascade Microtech Singapore phone: +65-6873-7482 email: cms\_sales@cmicro.com

Cascade Microtech Taiwan phone: +886-3-5722810 email: cmt\_sales@cmicro.com

